



Location

Beckman Conference Center
National Academies of Sciences & Engineering
Irvine, California, USA

Important Dates

December 20, 2006
Submission due
January 20, 2007
Notification of acceptance
February 20, 2007
Final papers

Organization

IFIP - <http://www.ifip.org/>

Conference Theme

Over recent years, embedded systems have gained an enormous amount of processing power and functionality. Many of the formerly external components can now be integrated into a single System-on-Chip. This trend has resulted in a dramatic reduction in the size and cost of embedded systems. As a unique technology, the design of embedded systems is an essential element of many innovations.

Embedded systems meet their performance goals, including real-time constraints, through a combination of special-purpose hardware and software components tailored to the system requirements. Both the development of new features and the reuse of existing intellectual property components are essential to keeping up with ever demanding customer requirements. Furthermore, design complexities are steadily growing with an increasing number of components that have to cooperate properly. Embedded system designers have to cope with multiple goals and constraints simultaneously, including timing, power, reliability, dependability, maintenance, packaging and, last but not least, price. The significance of these constraints varies depending on the application area a system is targeted for. Typical embedded applications include multi-media, automotive, medical, and communication devices.

The goals of the International Embedded Systems Symposium are to present, exchange and discuss the state of the art, novel ideas, actual research results, and future tendencies in the field of embedded systems. Contributors and participants from both industry and academia are encouraged to take active part in this symposium.

Topics include but are not restricted to the following:

- Specification and modeling of embedded systems
- Design methodology for embedded systems
- Validation and verification of embedded systems
- New technologies and trends for embedded systems
- Hardware/software co-design
- Re-configurable architectures and applications
- Software synthesis for embedded systems
- Dependability and fault tolerance
- Power management and optimization
- Network and communication systems
- Distributed and modular controller architectures
- Case studies of embedded systems (e.g. automotive and medical applications)

Submission should consist of:

Cover page including most appropriate topic, title of the paper, names and affiliations of authors, contact author's name, address, phone number, fax number, and email address.

The paper (up to 10 pages in 11 point or larger) or an abstract (3 - 5 pages), which should provide a summary of the main results and their details to allow the program committee to assess their merits and significance, including references and comparisons.

The contribution must be unpublished and not submitted for publication elsewhere, including journals and the proceedings of other symposia or workshops. One author of each accepted paper should present it at the conference.

The Proceedings will be published by Springer, the official publisher of IFIP. Full details on how to format your paper can be found at the IESS 2007 web site www.iess.org or the web site of the conference publisher, Springer: www.wkap.com/ifip/styles/

You can submit Postscript, PDF, or MS Word files to: IESS@iess.org

or hard copies to:

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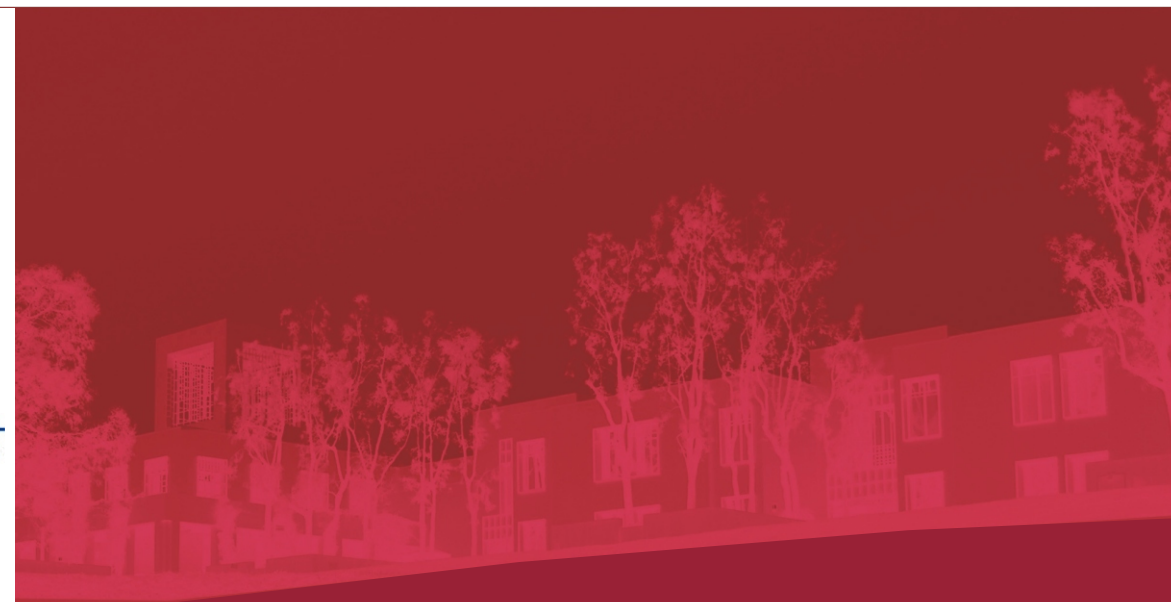
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IESS INTERNATIONAL EMBEDDED SYSTEMS SYMPOSIUM

call for papers
May 29 - June 1, 2007
Irvine, California, USA
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